

Si4356-RX-434 STANDALONE RECEIVER MODULE Users' Guide

1. Overview

This document describes the basic use of the 4356-RX-434 small standalone receiver module. The schematic of the module is shown in Figure 1.



Figure 1. 4356-RX-434 Standalone Receiver Module Schematic

The module contains the Si4356 Standalone Sub-GHz Receiver RF IC, a Zener diode or LDO, a low-cost SMD crystal, and the 4-element discrete matching balun transformer. Because the Si4356 RF IC is pin configurable, the module can operate in RX mode with different configurations. Different carrier frequencies, data rates, modulation types, frequency deviations, and receiver bandwidths can be set by the configuration selector pins (SEL0–SEL3). These pins are connected to GND, VDD_RF, OUT0 (pin 12), or OUT1 (pin 14). The Si4356 provides the received RAW data on pin 14.

The receiver performance can be significantly improved by adding a low-pass filter to the RX data output. These optional RC components are represented by R3 and C5 in Figure 1. Component values have to be calculated based on the expected data rate, where DR=1/(2*pi*R*C). For 2.4 kbps, a good combination could be 1 k Ω with 47 nF. For 1 kbps, use 100 nF.

The element values of the 4-element discrete matching balun transformer depend on the operating frequency. The

element values can be found in the Si4356 data sheet and are detailed in "AN643: Si446x/Si4362 RX LNA Matching".

The module is +5 V compatible; therefore, supply voltages up to +5 V can be connected to the VDD. Meanwhile, the Si4356 RF IC does not tolerate voltages above +3.6 V (VDD_RF). This voltage conversion between the VDD and VDD_RF (see Figure 1) is ensured by a Zener diode or an LDO; one of them should be mounted simultaneously. Do not directly connect +5 V to the pins of the Si4356 RF IC! The default and typical supply voltage for the VDD is +5 V while using an LDO to drive 3.3 V for the Si4356 RF IC (VDD_RF). If using a Zener diode, the R1 resistor value must be determined according to the Zener diode and the supply voltages.

The RST pin of the Si4356 RF IC on the small RX module is directly connected to the GND, which means that it is not possible to reset the radio chip externally. For this reason, it is strongly recommended to ensure the exact VDD requirements for the radio chip for a proper power-on-reset (POR), as documented in the Si4356 data sheet.

If the documented radio VDD requirements are not carefully followed for a proper POR, and if the VDD_RF is not stable, then it is recommended to place some very large valued capacitors (100 of μ F range) on the VDD and VDD_RF lines in order to avoid any unintentional "reset" due to the unstable VDD_RF (and the lack of the proper POR) that could get the radio chip into an undefined state.



2. Module Layout

The layout of the module is shown in Figure 2. The PCB is approximately 11x45 mm.





The module has two 4-pin connectors (see J1 and J2 in Figure 2), and the pin assignments are listed in Table 1.

Table 1. Standalone	Receiver Modu	le Pin Assi	anments
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J1		J2	
1	50 Ω point, antenna can be con- nected through this pin	1	Supply voltage
2	Ground	2	Not connected (default) or CLK
3	Ground	3	Received Data
4	Supply voltage	4	Ground



As the VDD is pulled up to +5 V, the module starts to work in RX mode, and all detectable signals at the selected frequency are demodulated and passed to the system MCU via the RX Data (pin 3 of J2).

The module has a 50 Ω input point (pin 1 of J1) where a monopole type antenna can be connected through pin 1 of the J1 connector.

Notes:

- A 15 MHz microcontroller clock output is available on pin 10 of the Si4356. This clock signal can be used to drive an
 external MCU and avoid the need for additional oscillators in the application. If this clock signal is not used, it can be
 turned off by connecting pin 10 to pin 12. By default, this clock signal is turned off; to make it available on pin 2 of J2, the
 SJ17 solderable jumper should be cut.
- 2. Each of the configuration selector pins (SEL0–SEL3) are connected to four solderable jumpers connected to GND, VDD_RF, OUT0, and OUT1. With these solderable jumpers (zoomed in Figure 3), the desired configuration can be set.

Figure 3 shows the solderable jumper connections.



*Note: These pins of the solderable jumpers are connected to GND through the R2 resistor (10 k Ω) to avoid excess current

Figure 3. Top- and Bottom-Layer Configuration Selector Pin Solderable Jumper Connections

Please refer to the data sheet of the Si4356 RF IC for information on how these solderable jumpers should be connected for all available configurations. The default configuration of the module is as follows:

- 1. Frequency: 433.92 MHz
- 2. Modulation Type: OOK
- 3. Data rate: 0.5–5 kbps
- 4. RX Bandwidth: 206 kHz

The manufacturing pack, including the CAD, CAM, BOM, and PDF files of the module, can be found on the Silicon Labs home page: www.silabs.com. More detailed information about the Si4356 RF IC can be found in the data sheet.



NOTES:





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